

Low-Voltage Dual SPDT Analog Switch UM3257 DFN12 3.0×1.6

General Description

The UM3257 is dual SPDT analog switch fabricated with silicon gate CMOS technology. It achieves very low propagation delay and $R_{DS(ON)}$ resistances while maintaining CMOS low power dissipation. These make it ideal for portable and battery power applications.

The switch conducts signals within power rails equally well in both directions when on, and blocks up to the power supply level when off. Break-before-make is guaranteed.

The select pin has over-voltage protection that allows voltages above V_{CC} , up to 6.5V to be present on the pin without damage or disruption of operation of the part, regardless of the operating voltage.

The UM3257 can maintain low power consumption for rail-to-rail signaling as long as the control signal input is held at a level that is greater than V_{IH} minimum and less than V_{IL} maximum by improving the control circuitry input buffer. so the part can be used in mixed voltage rail environments, especially services the mobile handset applications very well allowing for the direct interface with baseband processor general purpose I/Os, and it is no longer necessary to have the control input equal to V_{CC} to maintain low power consumption

The UM3257 is in a 12-pin, ROHS compliant, DFN12 package. It measures 3.0×1.6 mm. The leads are spaced at a pitch of 0.5mm and are finished with lead free Ni-Pd. The small package makes it ideal for use in portable electronics such as cell phones, digital cameras and PDAs.

Features

Applications

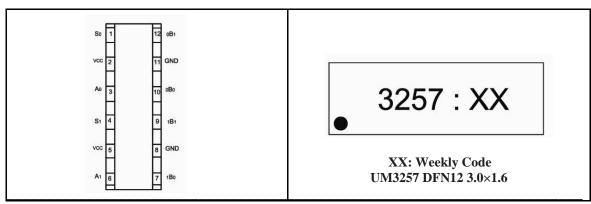
- Sample-and-Hold Circuits
- Battery powered Equipment
- Audio and Video Signal Routing
- Communication Circuits

Lower I_{CC} when the S Input is within the required V_{IH} and V_{IL} bounds

- Low ON-State Resistance (10Ω)
- Control Inputs Are 5V Tolerant
- Low Charge Injection
- Excellent ON-State Resistance Matching
- Low Total Harmonic Distortion (THD)
- 1.65V to 5.5V Single-Supply Operation
- ESD Performance: Human Body Model>2KV Machine Model>200V
- DFN12 Package
- Pb-Free Package

Pin Configurations







Ordering Information

Part Number	Packaging Type	Marking Code	Shipping Qty
UM3257	DFN12 3.0×1.6	3257	3000pcs/7 Inch Tape & Reel

Function Table

Select Input	Function			
L	B0 Connected to A			
Н	B1 Connected to A			

Absolute Maximum Ratings

Symbol	Parameter	Limit	Unit		
V _{CC}	Supply Voltage	- 0.5 to + 6.5			
V _{IS}	DC Switch Input Voltage (Note 1)	- 0.5 to $(V_{CC} + 0.5)$	V		
V_{IN}	DC IN Voltage (Note 1)	- 0.5 to + 6.5			
I _{IK}	DC Input Diode Current@ V _{IN} <0V	-50			
I _{OUT}	DC Output Current	128	mA		
I_{CC}/I_{GND}	DC V _{CC} or Ground Current	+100	1		
T _J	Junction Temperature Under Bias	+150			
T _{STG}	Storage Temperature	- 65 to +150	°C		
T _L	Junction Lead Temperature (Soldering, 10seconds)	260	C		
θ_{JA}	Thermal Resistance	350	°C/W		
P _D	Power Dissipation @ +85°C	180	mW		

1: The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

Recommended Ratings (Note2)

Symbol	Parameter	Limit	Unit
V _{CC}	Supply Voltage Operating	1.65 to 5.5	
V _{IS}	Switch Input Voltage	0 to V_{CC}	V
V _{IN}	Select Input Voltage	0 to V_{CC}	v
V _{OUT}	Output Voltage	0 to V_{CC}	
T _A	Operating Temperature	-55 to +125	°C
t _r , t _f	Input Rise and Fall Time Control Input Vcc=2.3V to 3.6V Control Input Vcc=4.5V to 5.5V	0 to 10 0 to 5.0	ns/V

2: Select input must be held HIGH or LOW, it must not float.



Electrical Characteristics

Symbol Parame	Parameter		s Vcc(V)	Temp	Limits (-40 to 85 °C)			T
	Parameter	Test Conditions			Min	Тур	Max	Unit
DC Elect	rical Characteristics							
	Analog Signal Range		Vcc	Full	0		V_{cc}	V
I _{IN}	Input Leakage Current	0≤ V _{IN} ≤ 5.5V	0 to 5.5	Room Full		±0.05	±0.1 ±1	μA
I _{OFF}	OFF State Leakage Current	0≤ A, B≤ Vcc	1.65 to 5.5	Room Full		±0.05	±0.1 ±1	μA
V_{IH}	Input High Voltage		1.65 to 1.95 2.3 to 5.5	Full	0.75Vcc 0.7Vcc			V
V_{IL}	Input Low Voltage		1.65 to 1.95 2.3 to 5.5	Full			0.25Vcc 0.3Vcc	V
I _{CC}	Quiescent Supply Current	$V_{IN} = Vcc \text{ or } GND$ $I_0 = 0$	5.5	Room Full			1.0 10	μA
		$V_{IN} = 0V, I_0 = 30mA$ $V_{IN} = 2.4V, I_0 = -30mA$ $V_{IN} = 4.5V, I_0 = -30mA$	4.5	Full		3.0 5.0 7.0	6.0 8.0 13	
R _{ON}	On-Resistance (Note3)	$V_{IN} = 0V, I_0 = 24mA$ $V_{IN} = 3V, I_0 = -24mA$	3.0	Full		4.0 10	8.0 19	Ω
		$V_{IN} = 0V, I_0 = 8mA$ $V_{IN} = 2.3V, I_0 = -8mA$	2.3	Full		5.0 13	9.0 24	
		$V_{IN} = 0V, I_0 = 4mA$ $V_{IN} = 1.65V, I_0 = -4mA$	1.65	Full		6.5 17	12 39	
		$I_A=-30mA$, 0≤ V_{Bn} ≤ Vcc	4.5	Full			25	
R _{RANGE}	On Resistance Over Signal Range	$I_A = -24 m A$, 0 $\leq V_{Bn} \leq V cc$	3.0	Full			50	Ω
	(Note3,7)	I_A =-8mA, 0≤ V_{Bn} ≤ Vcc	2.3	Full			100	
		I_A =-4mA, 0≤ V_{Bn} ≤ Vcc	1.65	Full			300	
		I_{A} =-30mA, V_{Bn} = 3.15V	4.5	Room		0.15		
ΔR_{ON}	On Resistance Match Between Channels	$I_A = -24 \text{mA}, V_{Bn} = 2.1 \text{V}$	3.0	Room		0.2		Ω
ΔK _{ON}	(Note3,4,5)	I_{A} =-8mA, V_{Bn} = 1.6V	2.3	Room		0.5		32
		I_A =-4mA, V_{Bn} = 1.15V	1.65	Room		0.5		
		$I_A = -30 \text{mA},$ $0 \le V_{Bn} \le \text{Vcc}$	5.0	Room		5.0		Ω
R _{FLAT}	On Resistance Flatness (Note3,4,6)	I _A =-24mA, 0≤ V _{Bn} ≤ Vcc	3.3	Room		10		
	(······, ····)	I_A =-8mA, 0≤ V_{Bn} ≤ Vcc	2.5	Room		24		
		$I_A = -4mA$, $0 \le V_{Bn} \le Vcc$	1.8	Room		110		

3: Measured by the voltage drop between A and B pins at the indicated current through the switch. On Resistance is determined by the lower of the voltages on the two (A or B Ports).

4: Parameter is characterized but not tested in production.

5: $\Delta R_{ON} = |R_{ON (A00Bn)} - R_{ON (A11Bn)}|$ measured at identical V_{CC}, temperature and voltage levels.

6: Flatness is defined as the difference between the maximum and minimum value of On Resistance over the specified range of conditions. 7: Guaranteed by Design.



Electrical Characteristics (Continued)

Symbol					Limits (-40 to 85 °C)			
Symbol	Parameter	Test Conditions	Vcc(V)	Temp	Min	Тур	Max	Unit
AC Electric	al Characteristics							
t _{PHL} t _{PLH}	Propagation Delay Bus to Bus (Note 9)	V ₁ = OPEN	1.65 to1.95 2.3 to 2.7 3.0 to 3.6 4.5 to 5.5	Room		1.2 0.8 0.3		ns
t _{PZL} t _{PZH}	Output Enable Time Turn On Time (A to Bn)	$V_{I} = 2 \times V_{CC} \text{ for } t_{PZL}$ $V_{I} = 0 \text{ V for } t_{PZH}$	1.65 to1.95 2.3 to 2.7 3.0 to 3.6 4.5 to 5.5	Full	7.0 3.5 2.5 1.7		32 14 7.6 5.7	ns
t _{plz} t _{phz}	Output Disable Time Turn Off Time (A Port to B Port)	$V_{I} = 2 \times V_{CC} \text{ for } t_{PLZ}$ $V_{I} = 0 \text{ V for } t_{PHZ}$	1.65 to1.95 2.3 to 2.7 3.0 to 3.6 4.5 to 5.5	Full	3.0 2.0 1.5 0.8		28 15 11 8	ns
t _{BBM}	Break Before Make Time (Note 8)	R_L =50 Ω , C_L =35 pF	1.65 to1.95 2.3 to 2.7 3.0 to 3.6 4.5 to 5.5	Full	0.5 0.5 0.5 0.5			ns
Q _{INJ}	Charge Injection (Note 8)	$C_{L} = 0.1 \text{ nF},$ $V_{GEN} = 0 \text{ V } R_{GEN} = 0\Omega$	5.0 3.3	Room		7.0 3.0		pC
O _{IRR}	Off Isolation (Note 10)	R_L =50 Ω , f = 10 MHz	1.65 to 5.5	Room		-55		dB
Xtalk	Crosstalk	R_L =50 Ω , f = 10 MHz	1.65 to 5.5	Room		-54		dB
BW	-3 dB Bandwidth	$R_L=50\Omega$	2.5 to 5.5	Room		250		MHz
THD	Total Harmonic Distortion (Note8)	$\begin{array}{c} R_{L}{=}600\Omega \\ 0.5V_{P.P} \\ f{=}600Hz \ to \ 20kHz \end{array}$	2.5 5.0	Room		0.014 0.004		%
Capacitanc	e							
C _{IN}	IN Pin Input Capacitance (Note11)	$V_{CC} = 0V$				2.3		pF
C _{IO-B}	B Port Off Capacitance (Note11)	$V_{CC} = 5.0 V$				6.5		pF
C _{IOA-ON}	A Port Capacitance when Switch is Enabled (Note11)	V _{CC} =5.0V				18.5		pF

8: Guaranteed by Design.

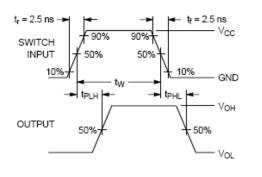
9: This parameter is guaranteed by design but not tested. The bus switch contributes no propagation delay other than the RC delay of 9. This parameter is guaranteed by design but not tested. The bus swhich contributes no propagation detay other than the KC detay the On Resistance of the switch and the 35 pF load capacitance, when driven by an ideal voltage source (zero output impedance). 10: Off Isolation = $20 \log_{10} [V_A/V_{Bn}]$. 11: $T_A = +25$, f = 1 MHz, Capacitance is characterized but not tested in production.



Test Circuits/Timing Diagrams







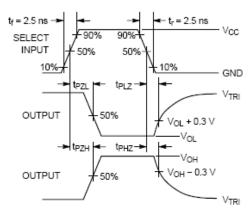
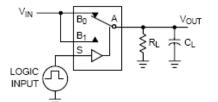


Figure 2. AC Waveforms



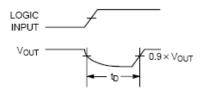


Figure 3. Break Before Make Interval Timing



50 Ω

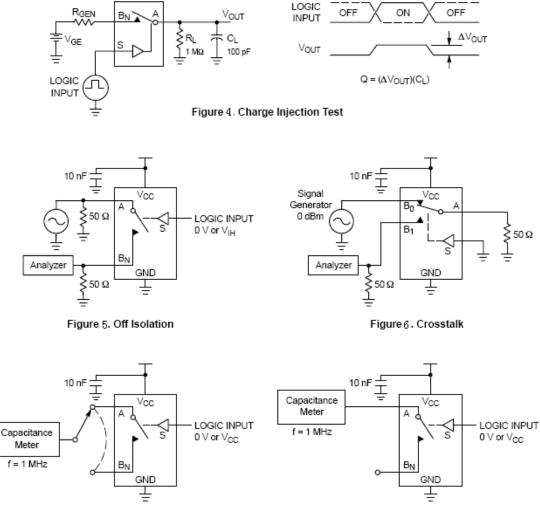
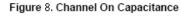


Figure 7 . Channel Off Capacitance



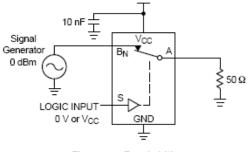


Figure 9. Bandwidth



6

4

2

0

0.0

0.5

1.0

1.5

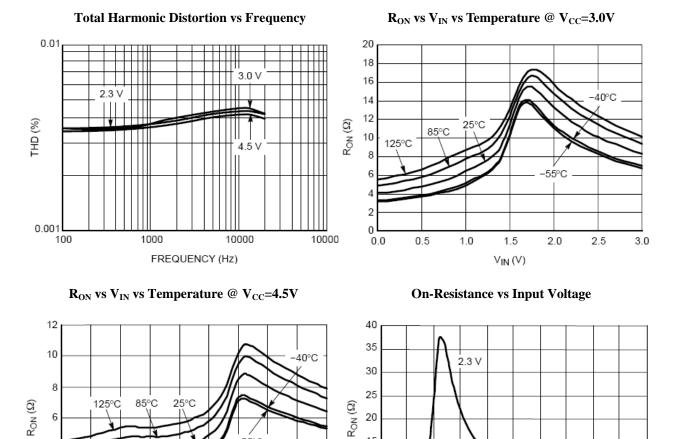
2.0

V_{IN} (V)

2.5



Typical Operating Characteristics



20 15

10

5

0.0

0.5

3.0 \

1.0 1.5 4.5 V

 $V_{\rm IN}(V)$

3.0 3.5 4.0 4.5 5.0

2.0 2.5

55°C

3.0

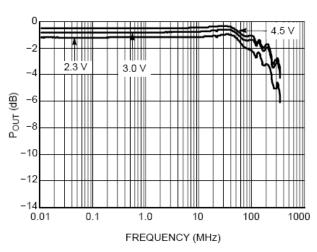
3.5

4.0

4.5

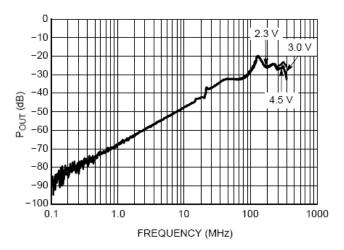


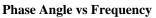
Typical Operating Characteristics (Continued)

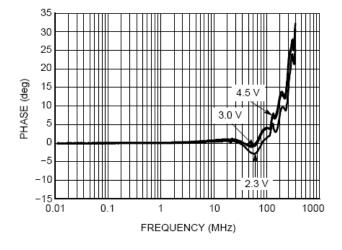


Bandwidth vs Frequency

Off-Isolation vs Frequency







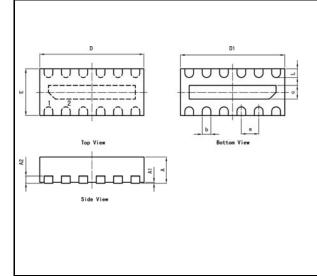




Package Information

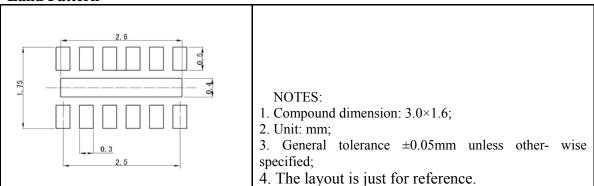
UM3257 DFN12 3.0×1.6

Outline Drawing



DIMENSIONS							
C11	MILLIN	1ETERS	INCHES				
Symbol	Min	Max	Min	Max			
А	0.700	0.800	0.028	0.031			
A1	0.000	0.050	0.000	0.002			
A2	0.153	0.253	0.006	0.010			
b	0.180	0.300	0.007	0.012			
c	0.300	0.500	0.012	0.020			
D	2.900	3.100	0.114	0.122			
D1	2.400	2.600	0.094	0.102			
Е	1.550	1.675	0.061	0.066			
e	0.450	0.550	0.018	0.022			
L	0.150	0.350	0.006	0.014			

Land Pattern



Tape and Reel Orientation





IMPORTANT NOTICE

The information in this document has been carefully reviewed and is believed to be accurate. Nonetheless, this document is subject to change without notice. Union assumes no responsibility for any inaccuracies that may be contained in this document, and makes no commitment to update or to keep current the contained information, or to notify a person or organization of any update. Union reserves the right to make changes, at any time, in order to improve reliability, function or design and to attempt to supply the best product possible.



Union Semiconductor, Inc Add: 7F, No. 5, Bibo Road, Shanghai 201203 Tel: 021-51097928 Fax: 021-51026018 Website: www.union-ic.com